

Bias Resistor Transistor

PNP Silicon Surface Mount Transistor with Monolithic Bias Resistor Network

• Applications

Inverter, Interface, Driver

• Features

- 1) Built-in bias resistors enable the configuration of an inverter circuit without connecting external input resistors (see equivalent circuit).
- 2) The bias resistors consist of thin-film resistors with complete isolation to allow positive biasing of the input. They also have the advantage of almost completely eliminating parasitic effects.
- Only the on/off conditions need to be set for operation, making the device design easy.
- We declare that the material of product compliance with RoHS requirements.

•Absolute maximum ratings (Ta=25°C)

Parameter	Symbol	Limits	Unit	
Supply voltage	Vcc	-50	V	
Input voltage	Vin	-10 to +5	V	
Output current	lo	- 100	mA	
	IC(Max.)	- 100		
Power dissipation	Po	200	mW	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

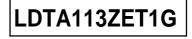
DEVICE MARKING AND RESISTOR VALUES

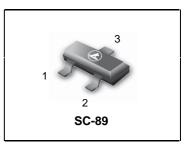
Device	Marking	R1 (K)	R2 (K)	Shipping	
LDTA113ZET1G	E8	1	10	3000/Tape & Reel	
LDTA113ZET3G	E8	1	10	10000/Tape & Reel	

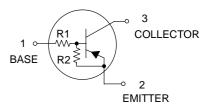
Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
1	VI(off)	—	_	-0.3	v	$Vcc=-5V$, $Io=-100 \mu A$
Input voltage	VI(on)	-3	_	-		Vo=-0.3V, Io=-20mA
Output voltage	VO(on)	_	-	-0.3	V	lo/li=-10mA/-0.5mA
Input current	li li	_	_	-7.2	mA	V1=-5V
Output current	IO(off)	—	-	-0.5	μA	Vcc=-50V, VI=0V
DC current gain	Gi	33	_	_	—	Vo=-5V,Io=-5mA
Input resistance	R1	0.7	1	1.3	kΩ	_
Resistance ratio	R2/R1	8	10	12	_	_
Transition frequency	fт	_	250	_	MHz	Vce=-10V, le=5mA, f=100MHz *

* Transition frequency of the device

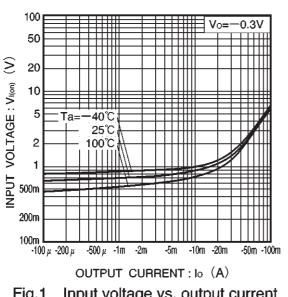




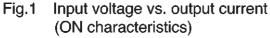


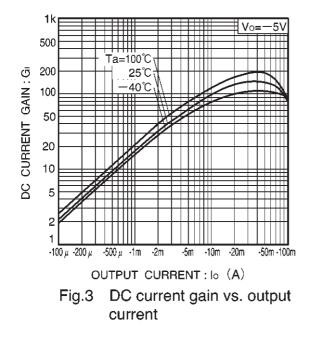


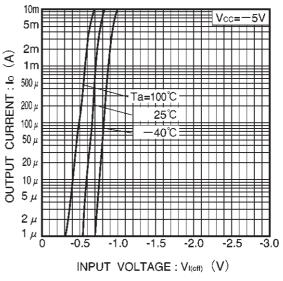
LDTA113ZET1G

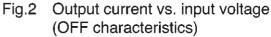


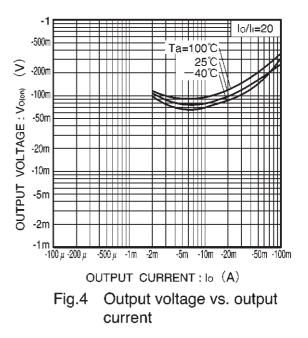
•Electrical characteristic curves







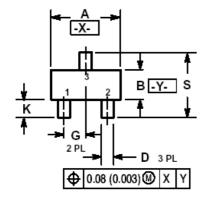






LDTA113ZET1G

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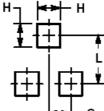
NOTES:

1.DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

2.CONTROLLING DIMENSION: MILLIMETERS 3.MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

4.463C-01 OBSOLETE, NEW STANDARD 463C-02.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.50	1.60	1.70	0.059	0.063	0.067	
В	0.75	0.85	0.95	0.030	0.034	0.040	
С	0.60	0.70	0.80	0.024	0.028	0.031	
D	0.23	0.28	0.33	0.009	0.011	0.013	
G	0.50 BSC			0.020 BSC			
H	0.53 REF			0.021 REF			
J	0.10	0.15	0.20	0.004	0.006	0.008	
K	0.30	0.40	0.50	0.012	0.016	0.020	
L	1.10 REF			0.043 REF			
M			10 °			10 °	
N			10 °			10 °	
S	1.50	1.60	1.70	0.059	0.063	0.067	



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单击下面可查看定价,库存,交付和生命周期等信息

>>LRC(乐山无线电)